

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:

0901522210

Status:

Active

Overview:

cgrid_sl_products

Description:

2.54mm (.100") Pitch C-Grid III™ PC Board Connector, Dual Row, Right Angle, Straight PCB Pins 0.38μm (15μ") Gold (Au) Selective, 10 Circuits

Documents:

3D Model

Drawing (PDF)

RoHS Certificate of Compliance (PDF)

General

Product Family

Series

Application

Overview

Product Name

PCB Receptacles

90152

Board-to-Board

cgrid_sl_products

C-Grid III™

Physical

Circuits (Loaded)

Color - Resin

Glow-Wire Compliant

Guide to Mating Part

Keying to Mating Part

Lock to Mating Part

Material - Metal

Material - Plating Mating

Material - Plating Termination

Material - Resin

Number of Rows

Orientation

PC Tail Length (in)

PC Tail Length (mm)

PCB Locator

PCB Retention

PCB Thickness Recommended (in)

PCB Thickness Recommended (mm)

Packaging Type

Pitch - Mating Interface (in)

Pitch - Mating Interface (mm)

Plating min: Mating (μin)

Plating min: Mating (μm)

Plating min: Termination (μin)

Plating min: Termination (μm)

Polarized to PCB

Temperature Range - Operating

Termination Interface: Style

10

Black

No

No

None

No

Phosphor Bronze

Gold

Tin

Polyester

2

Right Angle

0.114 In

2.90 mm

No

None

0.062 In

1.60 mm

Tube

0.100 In

2.54 mm

15.2

0.38

120

3

No

-55°C to +125°C

Through Hole

Electrical

Current - Maximum per Contact

Grounding to PCB

Voltage - Maximum

3A

No

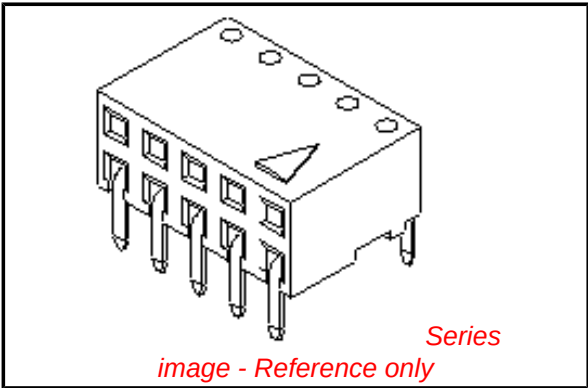
350V

Solder Process Data

Lead-free Process Capability

Wave Capable (TH only)

Material Info



EU RoHS

ELV and RoHS

Compliant

REACH SVHC

Contains SVHC: No

Halogen-Free

Status

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

90152Series

Mates With

90122 , 90131

Reference - Drawing Numbers

Sales Drawing

SDA-90152

This document was generated on 05/24/2010

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

F

E

D

C

B

A

F

E

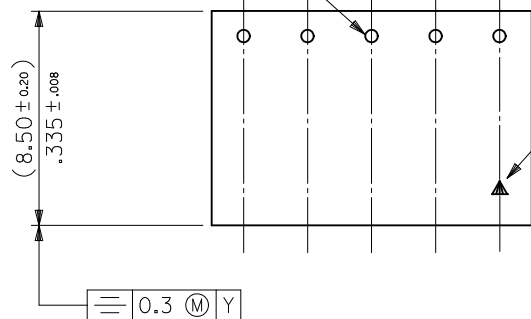
D

C

B

A

TERMINAL RETENTION FEATURE



SEE NOTE 4

(2.54)
.100

$\varnothing (0.80 \pm 0.05)$
.031 ± .004

$\varnothing (0.10) \pm .004$

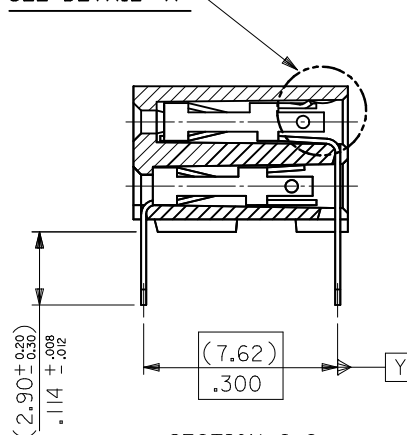
(7.62)
.300

RECOMMENDED P.C. BOARD
HOLE PATTERN

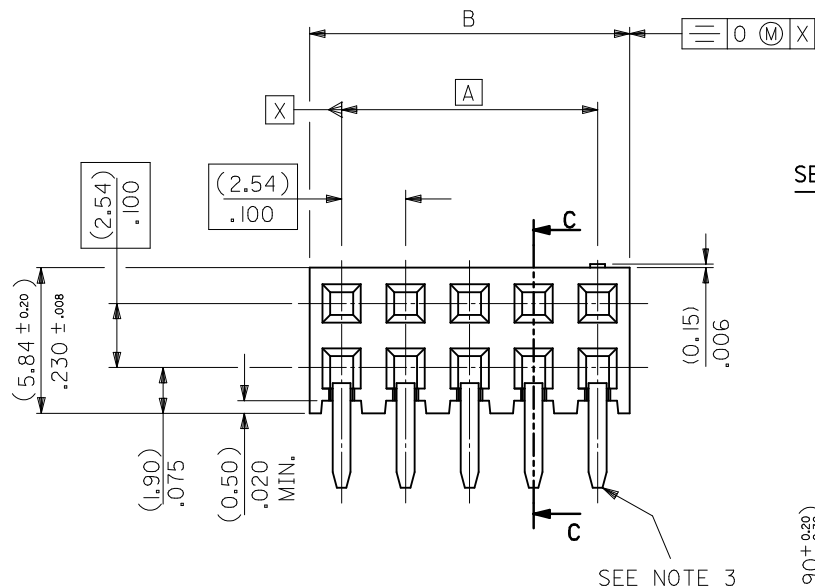
NOTES

- 1) CONTACT-PLATED PHOSPHOR BRONZE.
- 2) HOUSING-15% GLASS FILLED POLYESTER. COLOUR-BLACK.
- 3) COMPATABLE WITH PCB HOLE PATTERN.
- 4) THIS MARK INDICATES CIRCUIT NO.1.
- 5) FOR (0.635)/.025 SQ. MALE PINS THE LENGTH MUST BE (5.65)/.222 MIN & (7.00)/.276 MAX. TO ENSURE GOOD CONNECTION WITH CONTACT.
- 6) PRODUCT SPECIFICATION: PS-99020-0001
- 7) RECOMMENDED PCB THICKNESS 1.6MM

SEE DETAIL "A"

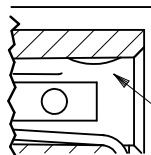


SECTION C-C



SEE NOTE 3

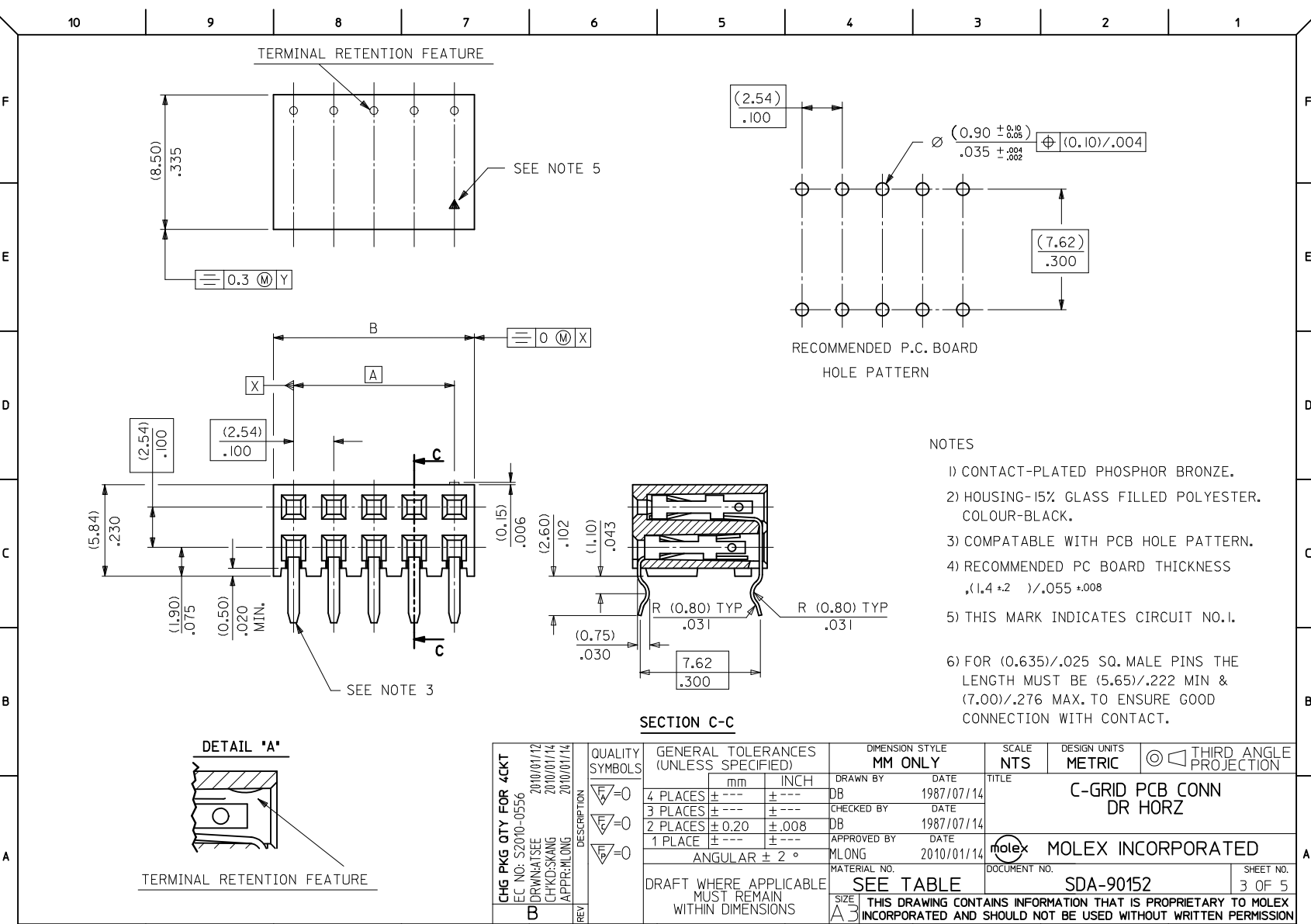
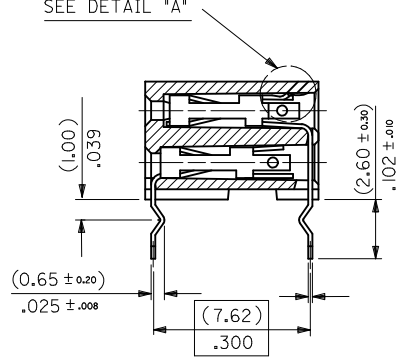
DETAIL "A"



TERMINAL RETENTION FEATURE

CHG PKG QTY FOR 4CKT				2010/01/12		DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
EC NO: S2010-0556				2010/01/14				mm		MM ONLY		NTS	METRIC			
DRWN:ATSEE				2010/01/14				INCH		DRAWN BY		DATE		TITLE		
CHKD:SKANG				2010/01/14						CHECKED BY		DATE		C-GRID PCB CONN		
APPR:MLONG							$F=0$	4 PLACES	$\pm \text{---}$	$\pm \text{---}$	DB	1987/07/14	DR HORZ			
							$F=0$	3 PLACES	$\pm \text{---}$	$\pm \text{---}$	DB	1987/07/14				
							$F=0$	2 PLACES	± 0.20	$\pm .008$	DB	1987/07/14				
							$F=0$	1 PLACE	$\pm \text{---}$	$\pm \text{---}$	APPROVED BY	DATE	MOLEX INCORPORATED			
								ANGULAR $\pm 2^\circ$		MLONG		2010/01/14	MOLEX INCORPORATED			
										MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
								DRAFT WHERE APPLICABLE		SEE TABLE		SDA-90152		1 OF 5		
								MUST REMAIN		SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX				
								WITHIN DIMENSIONS		A3		INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

	10		9		8		7		6		5		4		3		2		1	
F	PART NO.	CKT	DIM. A		DIM. B (^{+0.00} (-0.30) ^{+0.00} -0.12		PCS/ TUBE	PLATING VERSION A PRE-PLATED HOT DIP TIN 1.0 TO 2.5 microns (.00004" TO .00010").												F
	90152-XX04	4	(2.54)	.100	(5.08)	.200	109													
	06	6	(5.08)	.200	(7.62)	.300	73													
	08	8	(7.62)	.300	(10.16)	.400	55													
	10	10	(10.16)	.400	(12.70)	.500	44													
	12	12	(12.70)	.500	(15.24)	.600	36													
	14	14	(15.24)	.600	(17.78)	.700	31													
	16	16	(17.78)	.700	(20.32)	.800	27													
	18	18	(20.32)	.800	(22.86)	.900	24													
	20	20	(22.86)	.900	(25.40)	1.000	22													
E	22	22					20	PLATING VERSION E 1.27 TO 1.78 microns (.00005" TO .00007") NICKEL OVERALL, 0.38 TO 0.64 microns (.000015" TO .000025") GOLD ON CONTACT AREA (OVER NICKEL). 3 TO 5 microns (.00012" TO .00020") TIN ON SOLDER TAILS (OVER NICKEL).												E
	24	24	(27.94)	1.100	(30.48)	1.200	18													
	26	26	(30.48)	1.200	(33.02)	1.300	16													
	28	28					14													
D	30	30	(35.56)	1.400	(38.10)	1.500	14	PLATING VERSION F 1.27 TO 1.78 microns (.00005" TO .00007") NICKEL OVERALL, 0.76 TO 1.0 microns (.00003" TO .00004") GOLD ON CONTACT AREA (OVER NICKEL). 3 TO 5 microns (.00012" TO .00020") TIN ON SOLDER TAILS (OVER NICKEL).												D
	32	32					13													
	34	34	(40.64)	1.600	(43.18)	1.700	12													
	36	36	(43.18)	1.700	(45.72)	1.800	12													
	38	38	(45.72)	1.800	(48.26)	1.900	11													
	40	40	(48.26)	1.900	(50.80)	2.000	11													
	42	42					10													
	44	44	(53.34)	2.100	(55.88)	2.200	10													
C	46	46					10	PLATING VERSION G 1.27 TO 1.78 microns (.00005" TO .00007") NICKEL OVERALL, 0.125 TO 0.20 microns (.000005" TO .0000079") GOLD ON CONTACT AREA (OVER NICKEL). 3 TO 5 microns (.00012" TO .00020") TIN ON SOLDER TAILS (OVER NICKEL).												C
	48	48					9													
	50	50	(60.96)	2.400	(63.50)	2.500	8													
	52	52					8													
	54	54					8													
	56	56	(68.58)	2.700	(71.12)	2.800	7													
	58	58					7													
	60	60	(73.66)	2.900	(76.20)	3.000	7													
B	62	62					6	90152 - X X Y Y 												



- NOTES
- 1) CONTACT-PLATED PHOSPHOR BRONZE.
 - 2) HOUSING-15% GLASS FILLED POLYESTER, COLOUR-BLACK.
 - 3) COMPATABLE WITH PCB HOLE PATTERN.
 - 4) RECOMMENDED PC BOARD THICKNESS
(1.4 ± .2) / .055 ± .008
 - 5) THIS MARK INDICATES CIRCUIT NO.1.
 - 6) FOR (0.635) / .025 SO. MALE PINS THE LENGTH MUST BE (5.65) / .222 MIN & (7.00) / .276 MAX. TO ENSURE GOOD CONNECTION WITH CONTACT.

CHG PKG QTY FOR 4CKT EC NO: S2010-0556 DRWNAT/SEE 2010/01/12 CHKD:SKANG 2010/01/14 APPR:M LONG 2010/01/14 REV	QUALITY SYMBOLS F=0 F=0 F=0	GENERAL TOLERANCES (UNLESS SPECIFIED) <table><tr><td></td><td>mm</td><td>INCH</td></tr><tr><td>4 PLACES</td><td>± ---</td><td>± ---</td></tr><tr><td>3 PLACES</td><td>± ---</td><td>± ---</td></tr><tr><td>2 PLACES</td><td>± 0.20</td><td>± .008</td></tr><tr><td>1 PLACE</td><td>± ---</td><td>± ---</td></tr><tr><td colspan="3">ANGULAR ± 2 °</td></tr></table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.20	± .008	1 PLACE	± ---	± ---	ANGULAR ± 2 °			DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
				mm	INCH																				
			4 PLACES	± ---	± ---																				
			3 PLACES	± ---	± ---																				
			2 PLACES	± 0.20	± .008																				
1 PLACE	± ---	± ---																							
ANGULAR ± 2 °																									
DRAWN BY DB		DATE 1987/07/14		TITLE C-GRID PCB CONN DR HORZ																					
CHECKED BY DB		DATE 1987/07/14																							
APPROVED BY M LONG		DATE 2010/01/14		MOLEX MOLEX INCORPORATED																					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		DOCUMENT NO. SDA-90152		SHEET NO. 3 OF 5																			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																									

	10		9		8		7		6		5		4		3		2		1						
	PART NO.	CKT	DIM. A		DIM. B (+0.00 -0.30 +0.00 -0.12)		PCS/ TUBE																		
F	90152-XX04	4	(2.54)	.100	(5.08)	.200	109	PLATING VERSION A																	
	06	6	(5.08)	.200	(7.62)	.300	73	PRE-PLATED HOT DIP TIN																	
	08	8	(7.62)	.300	(10.16)	.400	55	1.0 TO 2.5 microns (.00004" TO .00010").																	
	10	10	(10.16)	.400	(12.70)	.500	44	PLATING VERSION E																	
	12	12	(12.70)	.500	(15.24)	.600	36	1.27 TO 1.78 microns (.00005" TO .00007") NICKEL																	
	14	14	(15.24)	.600	(17.78)	.700	31	OVERALL, 0.38 TO 0.64 microns (.000015" TO .000025")																	
E	16	16	(17.78)	.700	(20.32)	.800	27	GOLD ON CONTACT AREA (OVER NICKEL).																	
	18	18	(20.32)	.800	(22.86)	.900	24	3 TO 5 microns (.00012" TO .00020") TIN																	
	20	20	(22.86)	.900	(25.40)	1.000	22	ON SOLDER TAILS (OVER NICKEL).																	
	22	22					20	PLATING VERSION F.																	
	24	24	(27.94)	1.100	(30.48)	1.200	18	1.27 TO 1.78 microns (.00005" TO .00007") NICKEL																	
	26	26	(30.48)	1.200	(33.02)	1.300	16	OVERALL, 0.76 TO 1.0 microns (.00003" TO .00004")																	
D	28	28					14	GOLD ON CONTACT AREA (OVER NICKEL).																	
	30	30	(35.56)	1.400	(38.10)	1.500	14	3 TO 5 microns (.00012" TO .00020") TIN																	
	32	32					13	ON SOLDER TAILS (OVER NICKEL).																	
	34	34	(40.64)	1.600	(43.18)	1.700	12	PLATING VERSION G.																	
	36	36	(43.18)	1.700	(45.72)	1.800	12	1.27 TO 1.78 microns (.00005" TO .00007") NICKEL																	
	38	38	(45.72)	1.800	(48.26)	1.900	11	OVERALL, 0.125 TO 0.20 microns (.000005" TO .0000079")																	
C	40	40	(48.26)	1.900	(50.80)	2.000	11	GOLD ON CONTACT AREA (OVER NICKEL).																	
	42	42					10	3 TO 5 microns (.00012" TO .00020") TIN																	
	44	44	(53.34)	2.100	(55.88)	2.200	10	ON SOLDER TAILS (OVER NICKEL).																	
	46	46					10	90152-XXYY																	
	48	48					9	INDICATES NO. OF CIRCUITS.																	
	50	50	(60.96)	2.400	(63.50)	2.500	8	PLATING CODE.																	
B	52	52					8	31 = VERSION A.																	
	54	54					8	32 = VERSION E.																	
	56	56	(68.58)	2.700	(71.12)	2.800	7	33 = VERSION F.																	
	58	58					7	35 = VERSION G.																	
	60	60	(73.66)	2.900	(76.20)	3.000	7																		
	62	62					6																		
A	90152-XX64	64	(78.74)	3.100	(81.28)	3.200	5																		
CHG PKG QTY FOR 4CKT EC NO: S2010-0556 2010/01/12 DRWN:ATSE 2010/01/14 CHKD:SKANG 2010/01/14 APPR:MLONG								QUALITY SYMBOLS F=0 F=0 F=0		GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± .008 1 PLACE ± --- ± --- ANGULAR ± 2 °		DIMENSION STYLE MM ONLY DRAWN BY DATE DB 1987/07/14 CHECKED BY DATE DB 1987/07/14 APPROVED BY DATE MLONG 2010/01/14 MATERIAL NO. SIZE A3		SCALE NTS DESIGN UNITS METRIC THIRD ANGLE PROJECTION		C-GRID PCB CONN DR HORZ MOLEX MOLEX INCORPORATED SDA-90152 SHEET NO. 4 OF 5									
tb_frame_A3_P_AM_T Rev. F 2009/06/18								9		8		7		6		5		4		3		2		1	

PART NUMBER	CKT. SIZE	PIN VOID	KINKED PINS	NO. PER TUBE
90152-6234	2 X 17	21	NONE	12
90152-5242	2 X 21	5	NONE	10
90152-7130	2 X 15	NONE	1,2 & 29,30	14

NOTES

- 1) FOR DIMENSIONS SEE SHEET 1.
 2) THIS MARK INDICATES CIRCUIT NO.1.
 3) SOLDER TAIL OF TERMINAL IN VOIDED CAVITY MUST BE CROPPED AS SHOWN OR TERMINAL REMOVED.

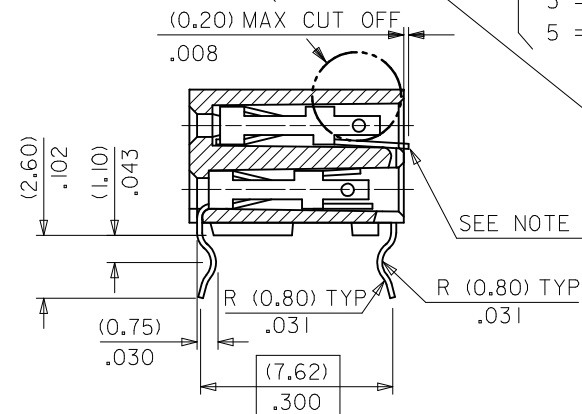
90152-XXYY

INDICATES NO. OF CIRCUITS.

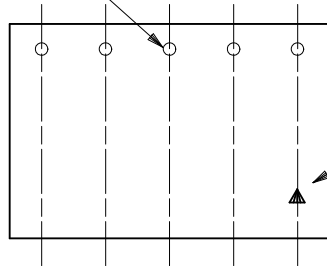
PLATING CODE.
 1 = VERSION A.
 2 = VERSION E.
 3 = VERSION F.
 5 = VERSION G.

OPTIONS
 2 = REGULAR
 3 = KINKED
 5 = VOIDS
 6 = KINKS & VOIDS
 7 = SELECTIVE KINKS

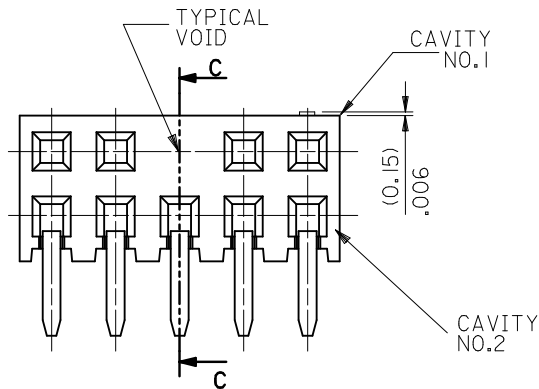
SEE DETAIL "A"



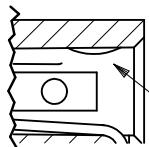
TERMINAL RETENTION FEATURE



SEE NOTE 2.



DETAIL "A"



TERMINAL RETENTION FEATURE

CHG PKG QTY FOR 4CKT			DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE		SCALE	DESIGN UNITS	 THIRD ANGLE PROJECTION	
EC NO: S2010-0556								MM ONLY		NTS	METRIC		
2010/01/12 DRWN:ATSEE					  	mm	INCH	DRAWN BY	DATE	TITLE C-GRID PCB CONN DR HORZ			
2010/01/14 CHKD:SKANG						4 PLACES	± ---	± ---	DB				1987/07/14
2010/01/14 APPR:MLONG						3 PLACES	± ---	± ---	CHECKED BY				DATE
						2 PLACES	± 0.20	± .008	DB				1987/07/14
					1 PLACE	± ---	± ---	APPROVED BY	DATE	 MOLEX INCORPORATED			
					ANGULAR ± 2 °			MLONG	2010/01/14				
					DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MATERIAL NO.					DOCUMENT NO.
								SEE TABLE		SDA-90152			5 OF 5
						SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
						A3							

SEE CHART

PART NO.

SDA-90152

DWG. NO.

PART NO.	NO.OF CKTS.	DIM. A		DIM. B ^{(+0.00 0.30 + .000 -.012}		NO. PER TUBE
90152-XX04	4	(2.54)	.100	(5.08)	.200	110
▲▲06	6	(5.08)	.200	(7.62)	.300	73
▲08	8	(7.62)	.300	(10.16)	.400	55
▲10	10	(10.16)	.400	(12.70)	.500	44
▲12	12	(12.70)	.500	(15.24)	.600	36
▲14	14	(15.24)	.600	(17.78)	.700	31
▲16	16	(17.78)	.700	(20.32)	.800	27
▲18	18	(20.32)	.800	(22.86)	.900	24
▲20	20	(22.86)	.900	(25.40)	1.000	22
▲22	22					20
▲24	24	(27.94)	1.100	(30.48)	1.200	18
▲26	26	(30.48)	1.200	(33.02)	1.300	16
▲28	28					14
▲30	30	(35.56)	1.400	(38.10)	1.500	14
▲32	32					13
▲34	34	(40.64)	1.600	(43.18)	1.700	12
▲36	36	(43.18)	1.700	(45.72)	1.800	12
▲38	38	(45.72)	1.800	(48.26)	1.900	11
▲40	40	(48.26)	1.900	(50.80)	2.000	11
▲42	42					10
▲44	44	(53.34)	2.100	(55.88)	2.200	10
▲46	46					10
▲48	48					9
▲50	50	(60.96)	2.400	(63.50)	2.500	8
▲52	52					8
▲54	54					8
▲56	56	(68.58)	2.700	(71.12)	2.800	7
▲58	58					7
▲60	60	(73.66)	2.900	(76.20)	3.000	7
▼▼62	62					6
90152-XX64	64	(78.74)	3.100	(81.28)	3.200	5

PLATING VERSION A

PRE-PLATED HOT DIP TIN
1.0 TO 2.5 microns (.00004" TO .00010").

PLATING VERSION E

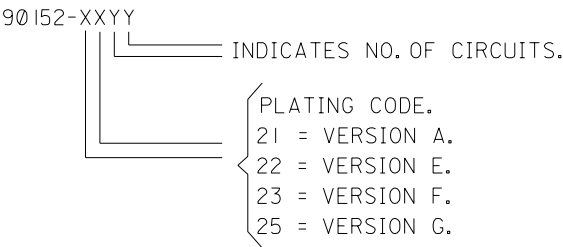
1.27 TO 1.78 microns (.00005" TO .00007") NICKEL
OVERALL, 0.38 TO 0.64 microns (.000015" TO .000025")
GOLD ON CONTACT AREA (OVER NICKEL).
3 TO 5 microns (.00012" TO .00020") TIN
ON SOLDER TAILS (OVER NICKEL).

PLATING VERSION F.

1.27 TO 1.78 microns (.00005" TO .00007") NICKEL
OVERALL, 0.76 TO 1.0 microns (.00003" TO .00004")
GOLD ON CONTACT AREA (OVER NICKEL).
3 TO 5 microns (.00012" TO .00020") TIN
ON SOLDER TAILS (OVER NICKEL).

PLATING VERSION G.

1.27 TO 1.78 microns (.00005" TO .00007") NICKEL
OVERALL, 0.125 TO 0.20 microns (.000005" TO .0000079")
GOLD ON CONTACT AREA (OVER NICKEL).
3 TO 5 microns (.00012" TO .00020") TIN
ON SOLDER TAILS (OVER NICKEL).



STANDARD PRODUCTS

FOR PREVIOUS
DRAWING ISSUES
SEE MRI.

LEAD FREE CONVERSION NEW BORDER ADDED EC NO. E2004-0610 DRAWN: PSHEAHAN 08/01/2004 CHK: APPR:		QUALITY SYMBOLS MAJOR CRITICAL	GENERAL TOLERANCES: (UNLESS SPECIFIED)		SCALE 5:1	DESIGN UNITS ☒ mm ☐ INCH	THIRD ANGLE PROJECTION	DIMENSIONS: ☐ mm ☐ INCH ☐ mm ONLY			SHT	REV		
AD			4 PLACES ±0.	±.	DRAWN BY & DATE DB 14/ 7/87	CHECKED BY & DATE		TITLE: C-GRID III DUAL ROW HORIZONTAL P.C. BOARD CONNECTOR			REVISE ON CAD ONLY			
REV		DESCRIPTION	3 PLACES ±0.	±.	APPROVED BY & DATE		MATERIAL NO. SEE CHART	MOLEX INCORPORATED			SHEET NO. 20F			
			2 PLACES ±0.	±.	CAD FILENAME			DRAWING NO. SDA-90152			SIZE B			
			1 PLACE ±0.	±.	ANGULAR: ± 0		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.							
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS											